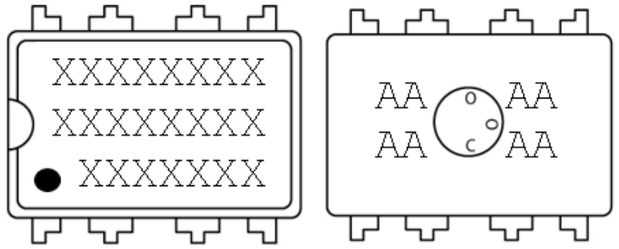
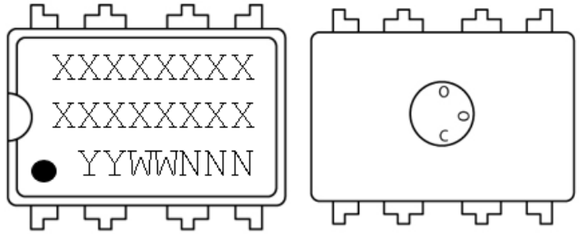
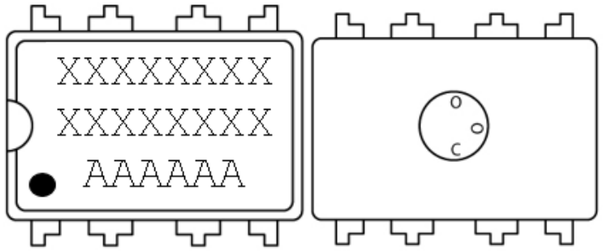
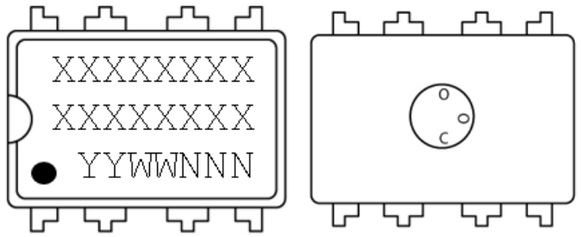
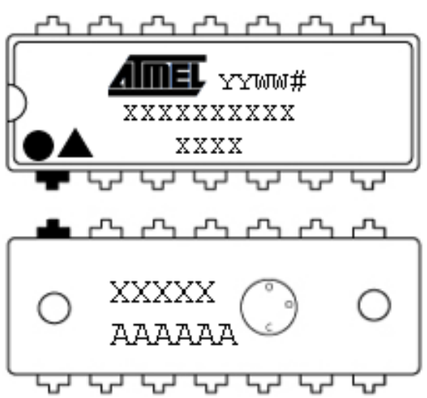
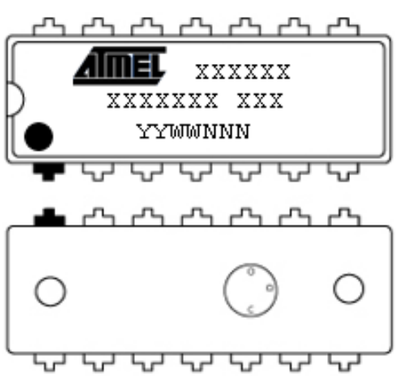
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	PDIP 300 MIL		**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code ● = Pin 1 indicator OR Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information **Bottom Mark** Lot Number Country of Origin in the injector mold		**Top Mark** Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability ● = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability ● = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information ● ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ●= Pin 1 location OR **Top Mark** Line 1= Atmel Logo, Device Information Line 2 = Device Name Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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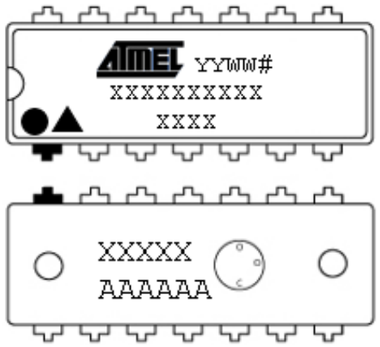
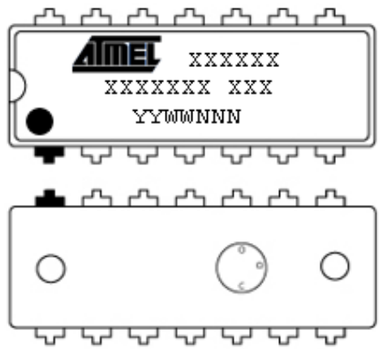
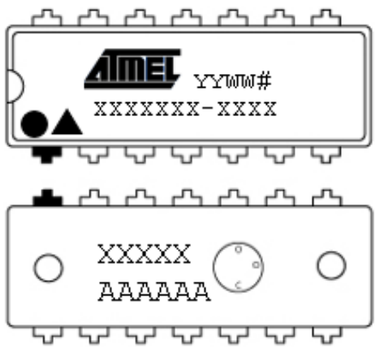
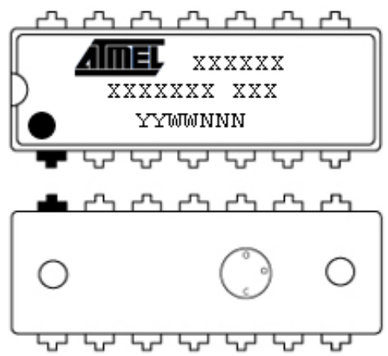
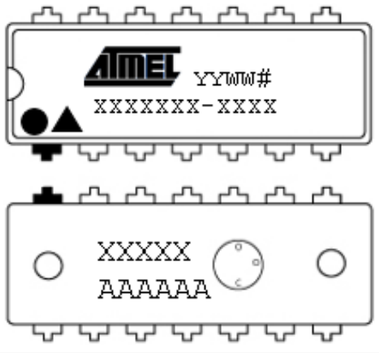
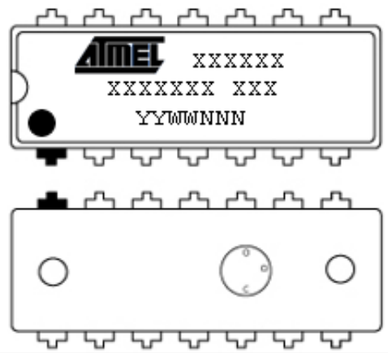
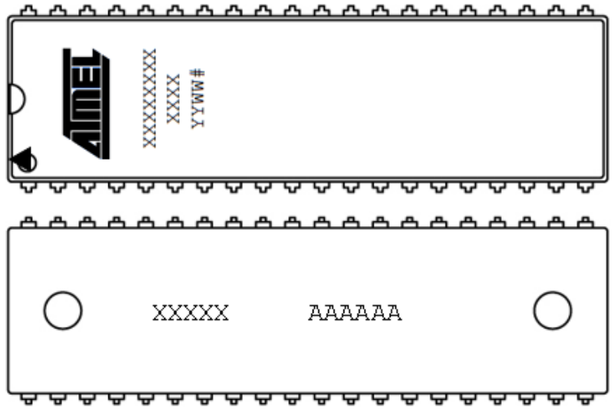
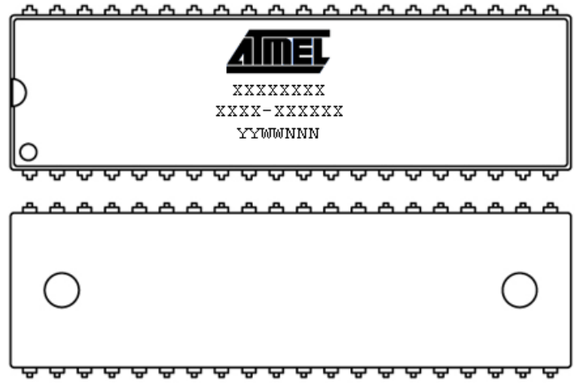
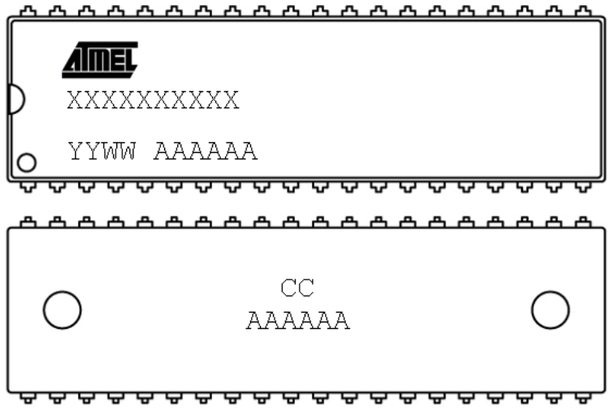
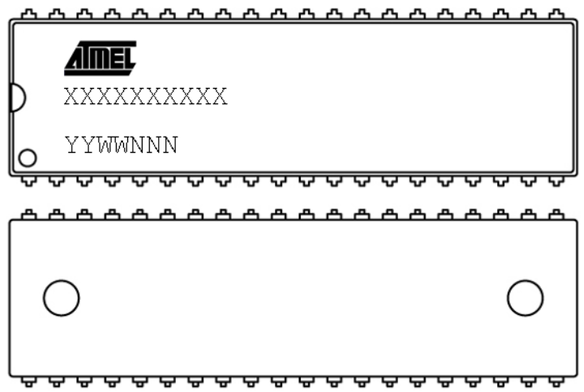
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
14	PDIP 300 MIL		**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ●= Pin 1 location **Bottom Mark** No bottom mark Country of Origin in injector mold
20	PDIP 300 MIL		**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ●= Pin 1 location OR **Top Mark** Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
24	PDIP300 MIL		**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability ●= Pin 1 location **Bottom Mark** No bottom mark Country of Origin in injector mold

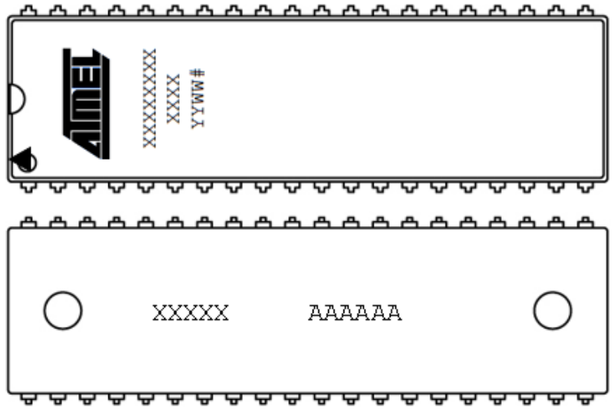
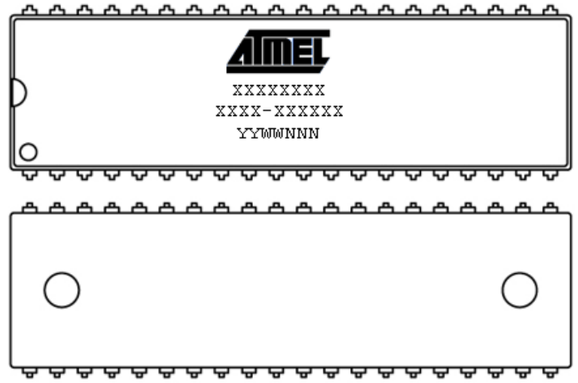
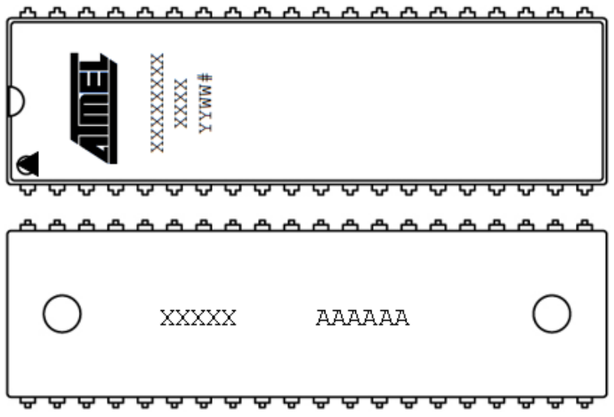
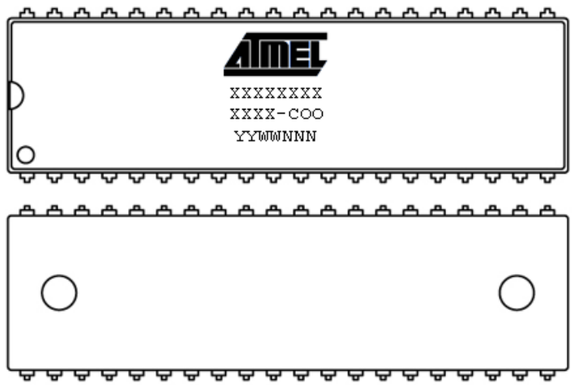
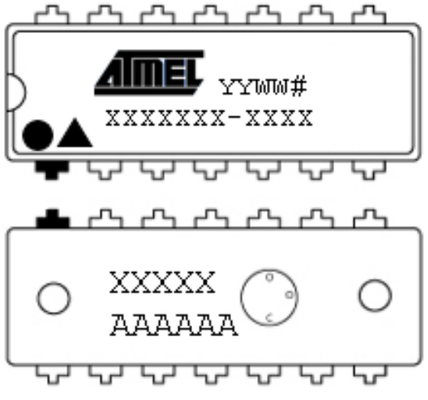
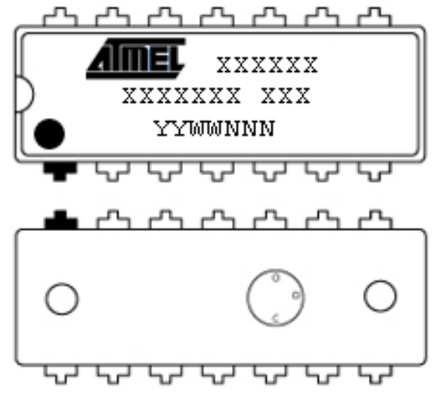
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
28 / 32	PDIP 600 MIL		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin in injector mold, Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator **Bottom Mark** No bottom mark
40	PDIP 600 MIL		**Top Mark** Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Line 2 = Lot Traceability		**Top Mark** Line 1= ATMEL Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold, Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold, Lot Traceability		**Top Mark** Line 1 = Atmel Logo Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No Bottom Mark
28	SPDIP		**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information ● ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Line 2 = Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability ●= Pin 1 location **Bottom Mark** No bottom mark Country of Origin in injector mold

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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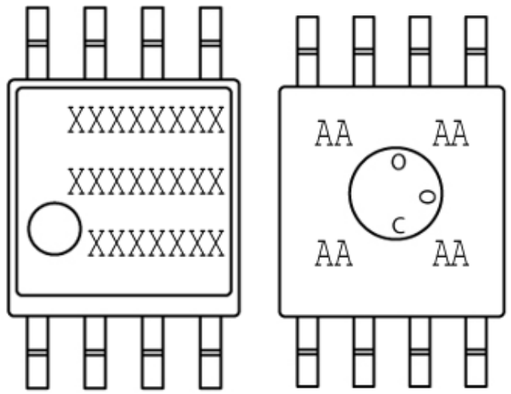
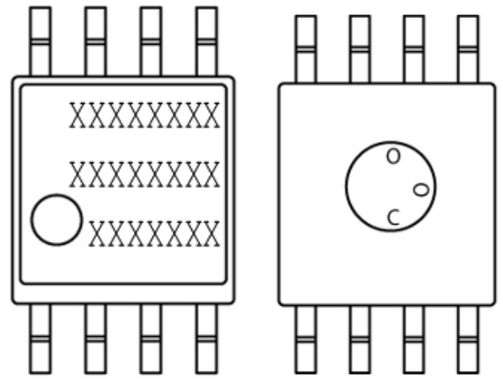
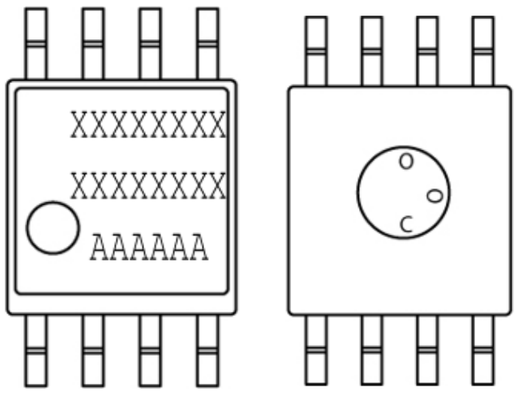
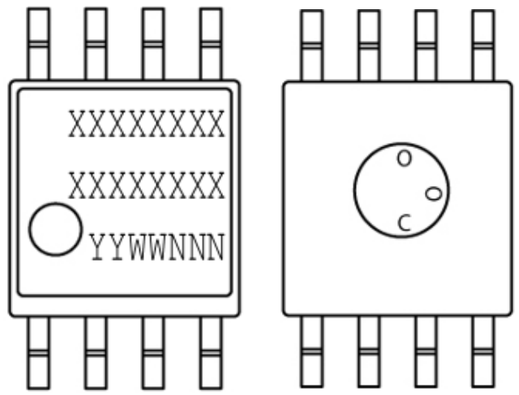
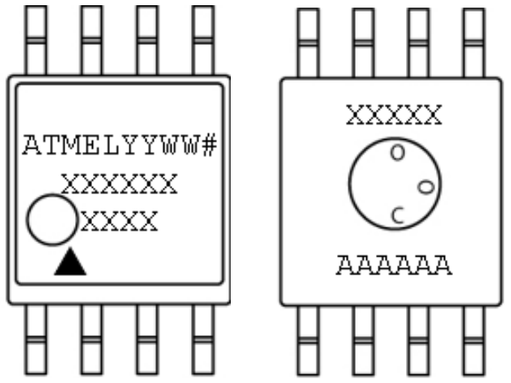
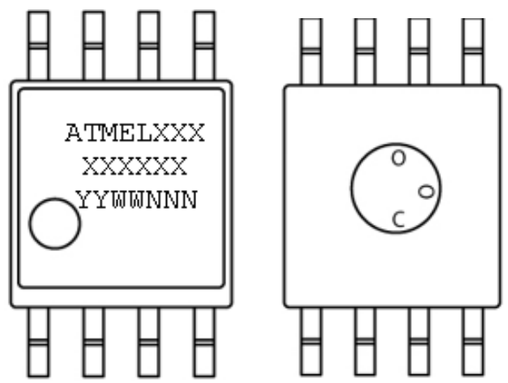
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	SOIJ		**Top Mark** Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator **Bottom Mark** Lot Number Country of Origin in the injector mold		**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Voltage Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O ▲ = Pin 1 indicator Bottom Mark Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator Bottom Mark No bottom mark Country of Origin in injector mold

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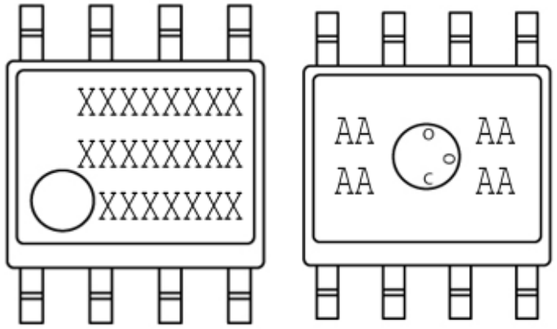
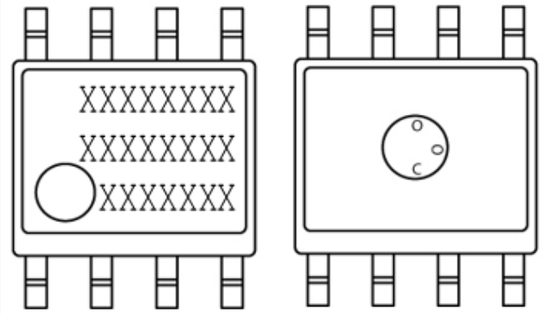
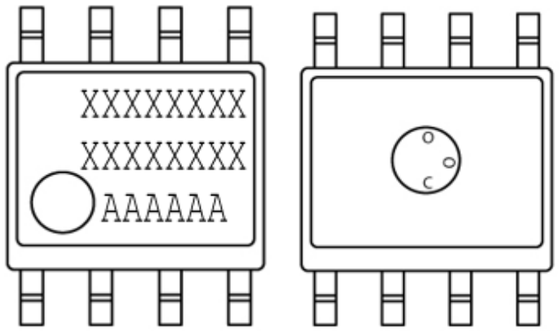
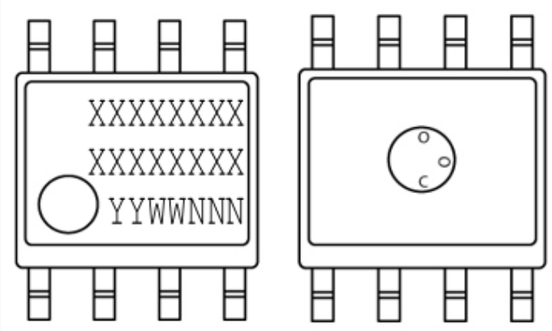
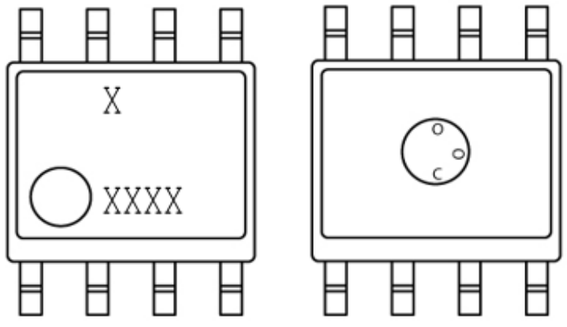
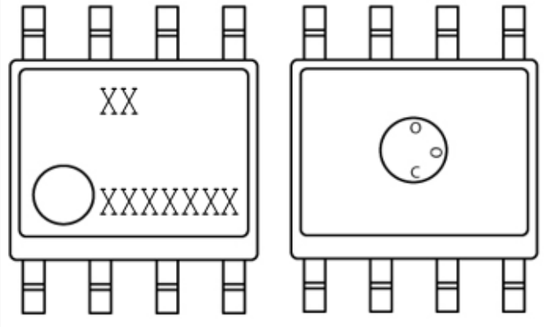
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	SOIC		**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Class Code, Date Code or Lot Traceability O = Pin 1 indicator **Bottom Mark** Lot Number Country of Origin in injector mold		**Top Mark** Line 1= Device Name, Class Code Line 2 = Device Information Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= ATMEL, Date Code Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Device Information Line 3 = Lot Traceability OR Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Subcon Code Line 2 = Date Code O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= Country of Origin Line 2 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

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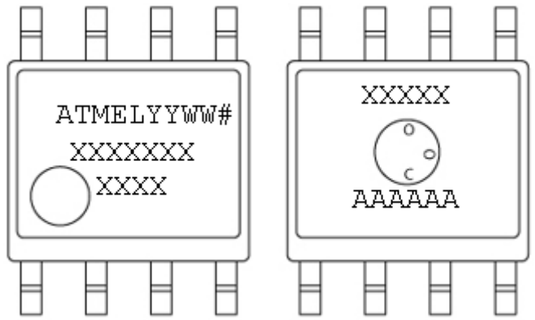
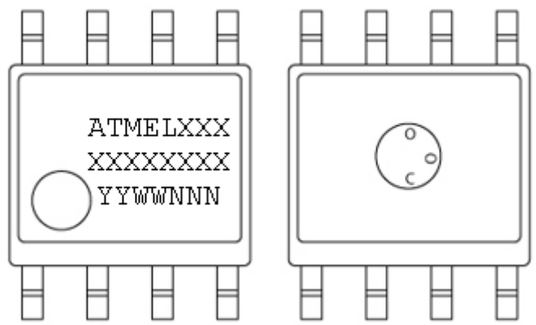
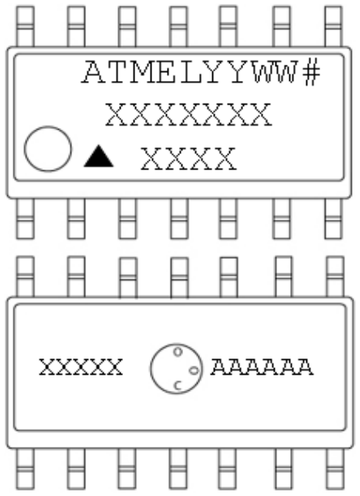
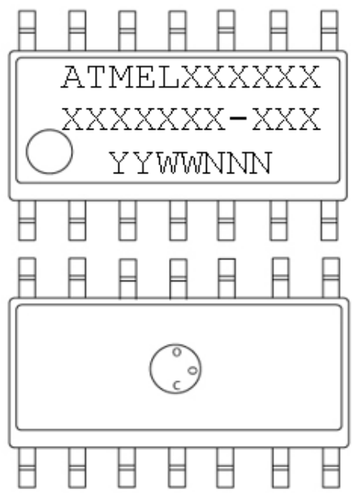
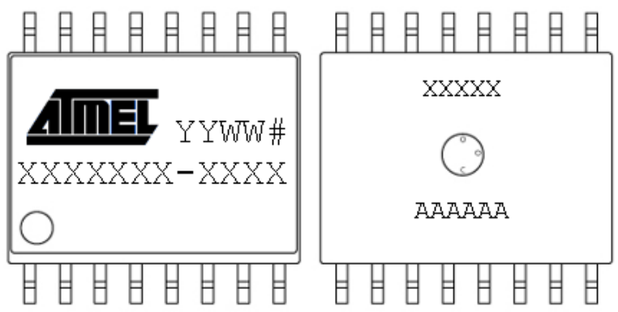
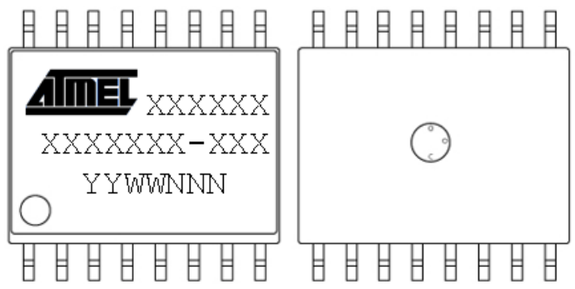
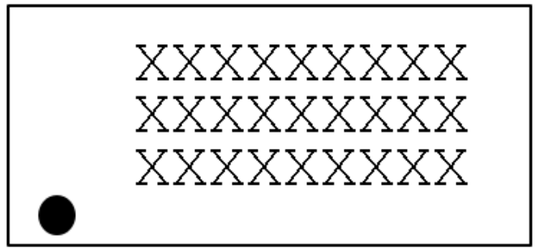
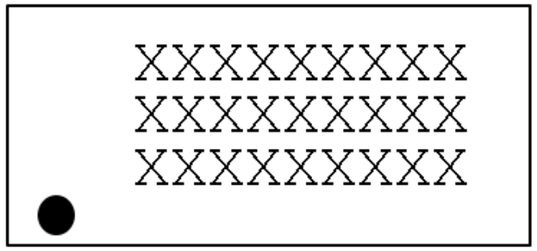
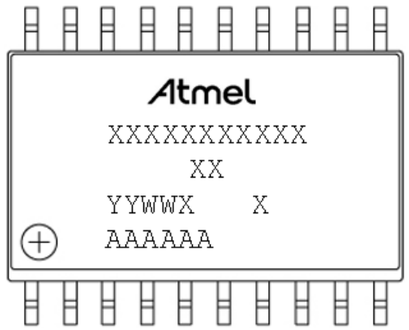
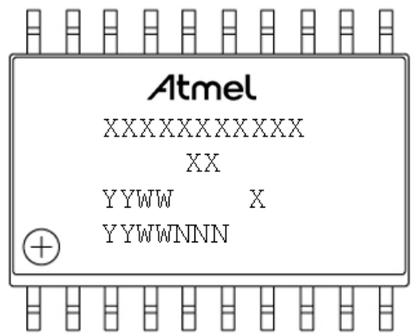
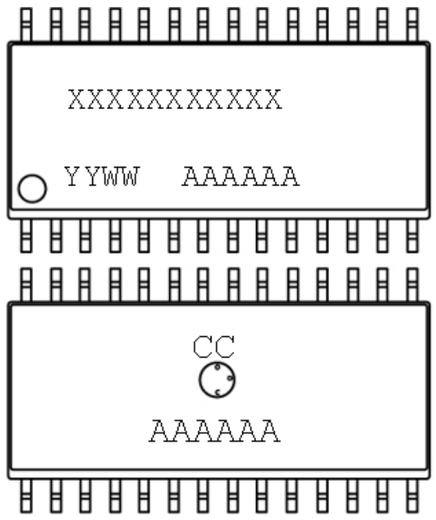
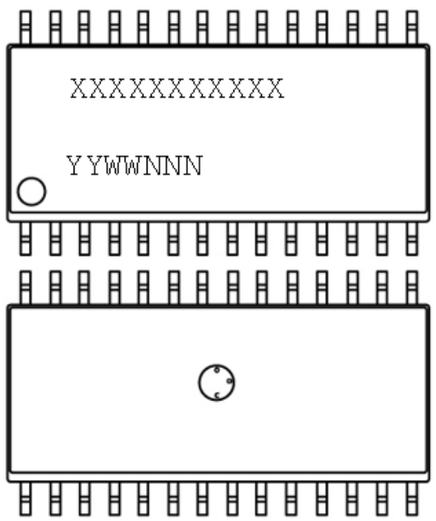
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = AAAAAAA = Lot Traceability		**Top Mark** Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
14	SOIC 150 MIL		**Top Mark** Line 1 = ATMEL, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O ▲ = Pin 1 indicator **Bottom Mark** XXXXX = Country of Origin if not in injector mold Country of Origin in injector mold AAAAAAA = Lot Traceability		**Top Mark** Line 1 = ATMEL, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
16 / 20 / 24 / 28	SOIC 300 MIL		**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator **Bottom Mark** Line 1 = XXXXX Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo, Die ID, Revision Line 2 = Device Name, Device Information Line 3 = Lot Traceability O = Pin 1 indicator OR **Top Mark** Line 1= Atmel Logo, Country of Origin Line 2 = Device Name, Device Information Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold

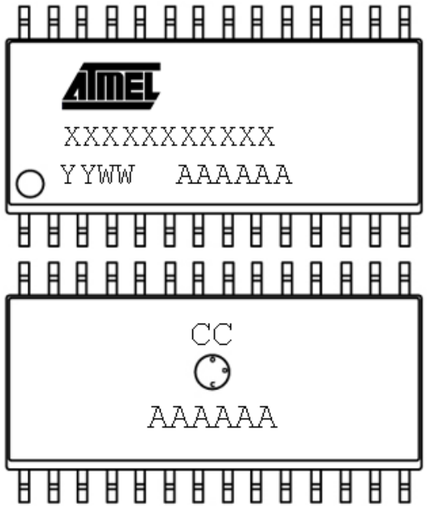
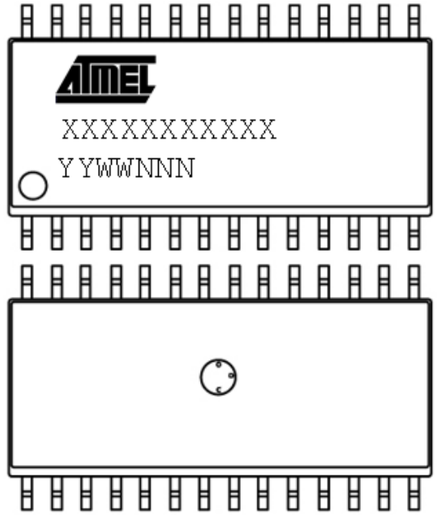
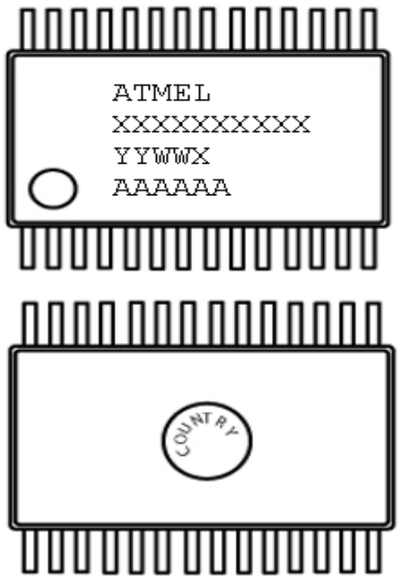
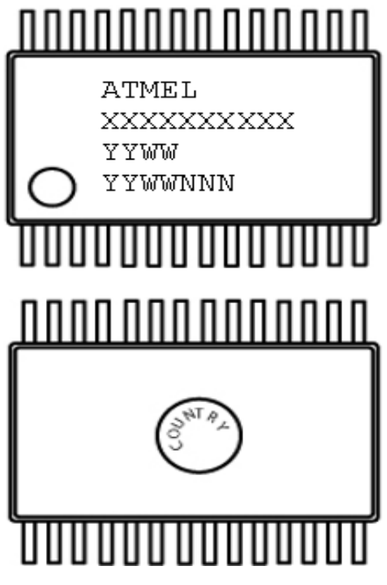
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code ● = Pin 1 indicator		**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Device Information, Date Code, Country of Origin ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability O = Pin 1 indicator
			**Top Mark** Line 1= Device Name Line 2 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Device Name Line 2 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

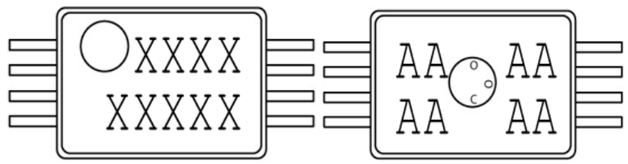
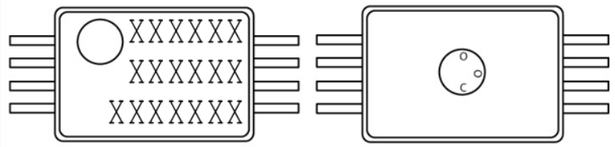
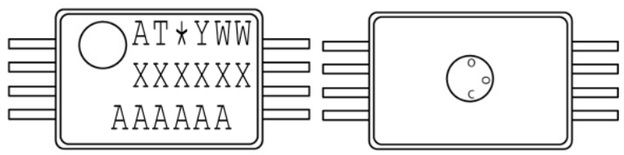
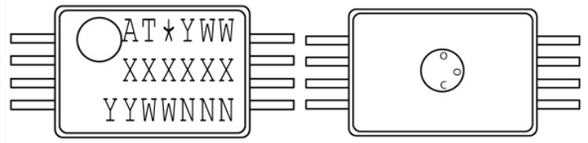
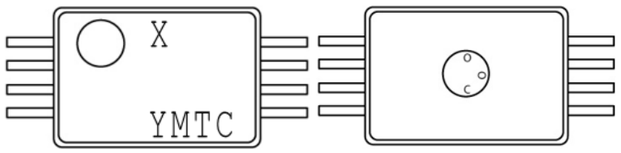
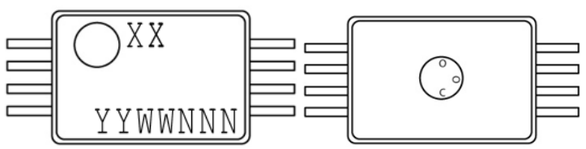
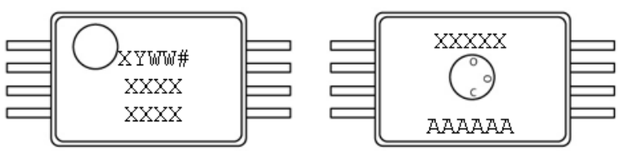
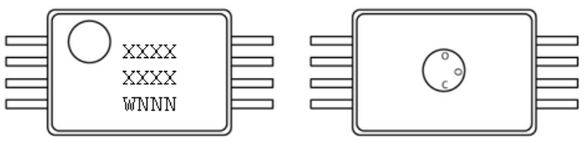
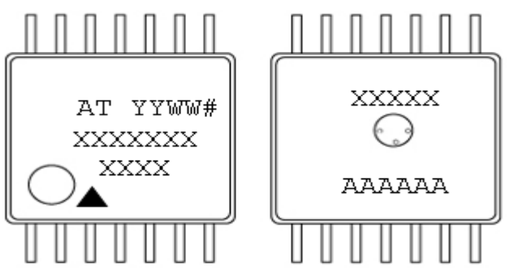
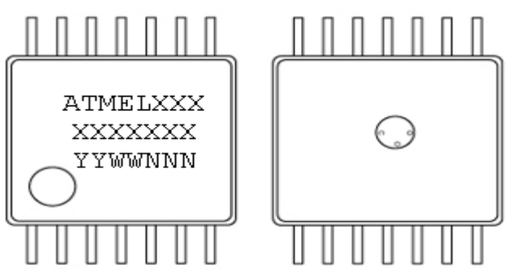
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country Code Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
28	SSOP 208 MIL		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code Line 4 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

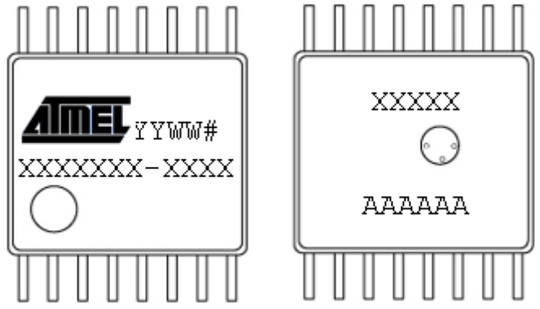
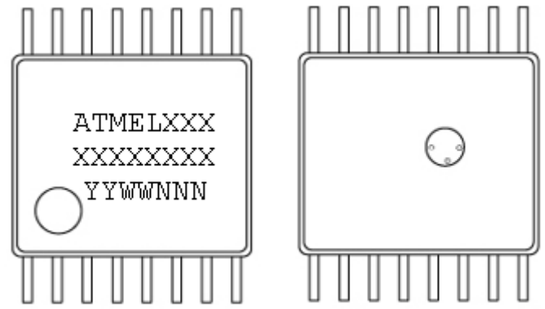
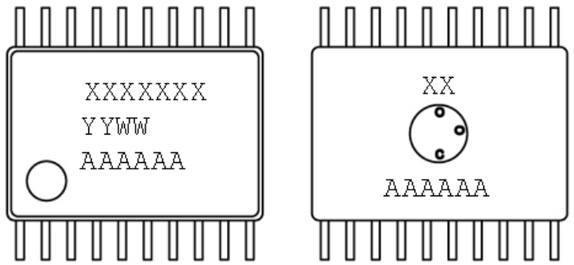
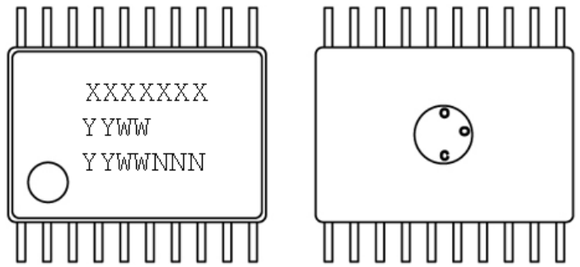
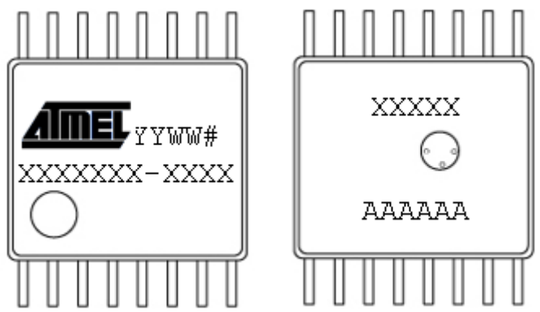
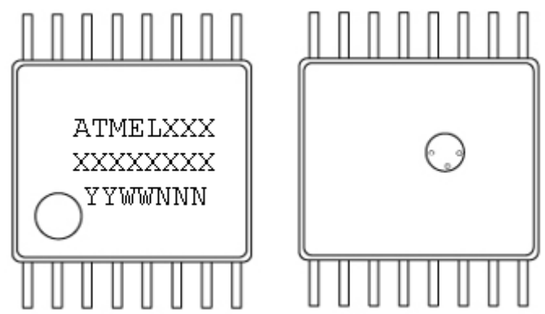
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
8	TSSOP		**Top Mark** Line 1= Class Code, Date Code Line 2 = Truncation Code O = Pin 1 indicator OR Line 1= Truncation Code Line 2 = Device Name **Bottom Mark** Lot Traceability Country of Origin in injector mold		**Top Mark** Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= AT, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= AT, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= Subcon Code Line 2 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= Country of Origin Line 2 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
			**Top Mark** Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name (shortened) Line 3 = Device Information **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1= Device Information Line 2 =Device Name (shortened) Line 3 = Lot Traceability **Bottom Mark** No bottom mark Country of Origin in injector mold
14	TSSOP		**Top Mark** Line 1 = AT, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information O = Pin 1 indicator ▲ = Pin 1 location **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

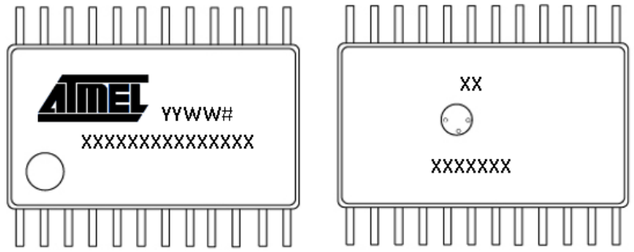
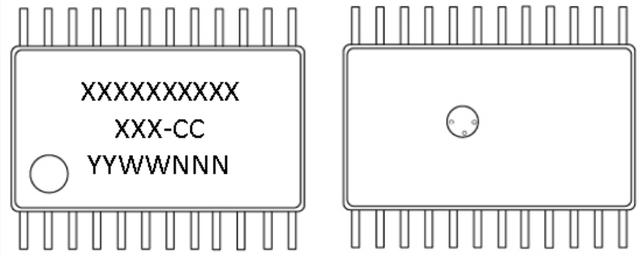
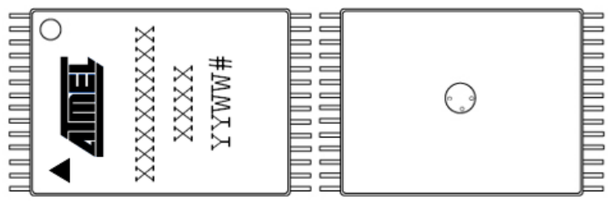
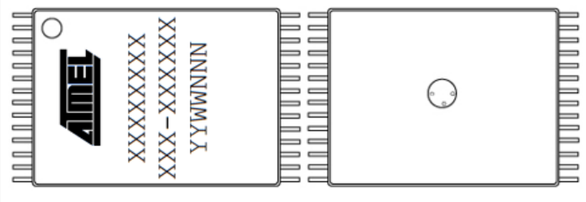
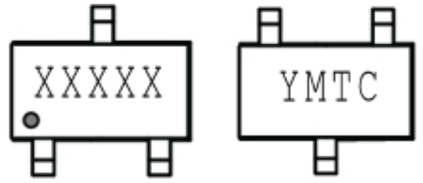
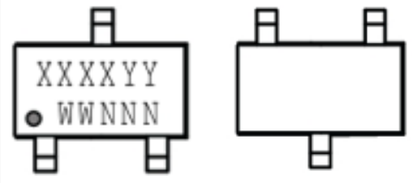
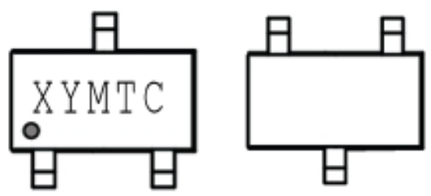
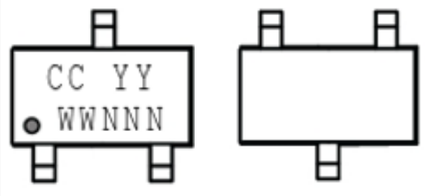
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
16	TSSOP		**Top Mark** Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
20	TSSOP		**Top Mark** Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** Country of Origin in injector mold
			**Top Mark** Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information O = Pin 1 indicator **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1 = ATMEL, Device Information Line 2 = Device Name Line 3 = Lot Traceability O = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold

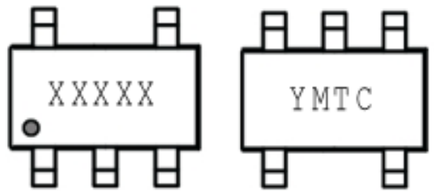
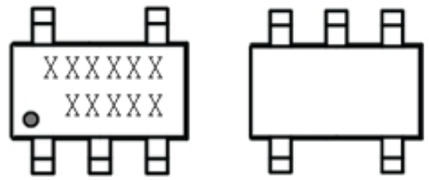
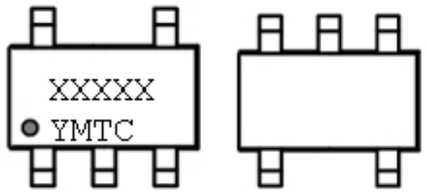
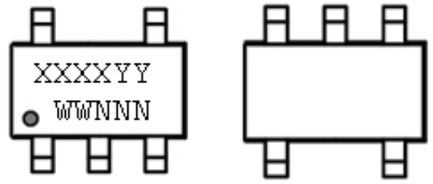
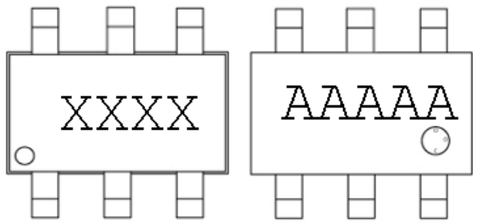
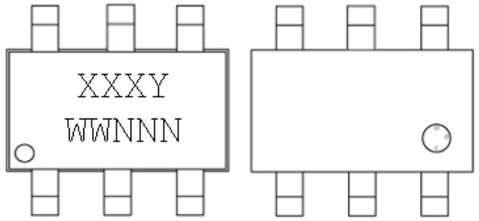
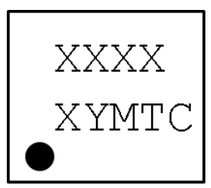
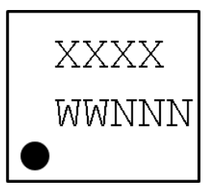
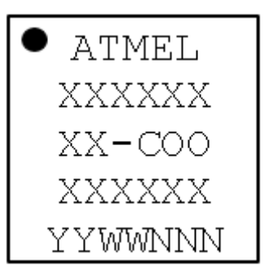
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
20 / 24	TSSOP		**Top Mark** Line 1 = ATMEL Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name, Device Information o = Pin 1 indicator **Bottom Mark** Line 1 = Country of Origin if not in injector mold Country of Origin in injector mold Line 2 = Lot Traceability		**Top Mark** Line 1 = Device Name Line 2 = Device Information, Country Code Line 3 = Lot Traceability o = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
28 / 32	TSOP		**Top Mark** Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, MRL (if shown in ABI) o = Pin 1 indicator ▲ = Pin 1 location **Bottom Mark** No bottom mark Country of Origin in injector mold		**Top Mark** Line 1 = ATMEL Logo Line 2 = Device Name Line 3 = Device Information, Die ID, Revision Line 4 = Lot Traceability o = Pin 1 indicator **Bottom Mark** No bottom mark Country of Origin in injector mold
	SOT-23		**Top Mark** Line 1= Truncation Code, Class Code ● = Pin 1 indicator **Bottom Mark** Lot Traceability (Year, Month, Trace Code)		**Top Mark** Line 1= Truncation Code, Subcon Code, Year Line 2 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Lot Traceability (Year, Month, Trace Code) **Bottom Mark** No bottom mark		**Top Mark** Line 1= Country Code, Year Line 2 = Lot Traceability **Bottom Mark** No bottom mark

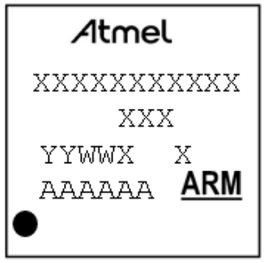
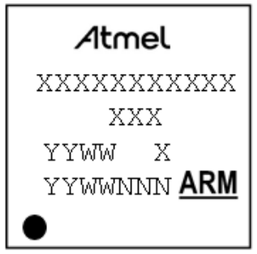
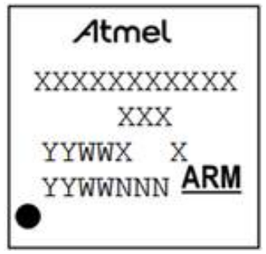
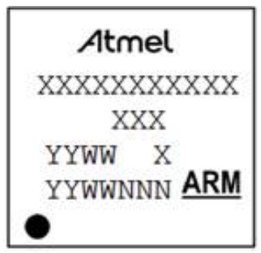
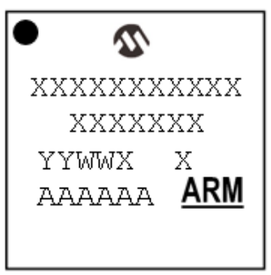
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
5	SOT-23		**Top Mark** Line 1= Truncation Code, Device Information ● = Pin 1 indicator **Bottom Mark** Lot Traceability (Year, Month, Trace Code)		**Top Mark** Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability (Workweek, Lot Number) ● = Pin 1 indicator **Bottom Mark** No bottom mark
			**Top Mark** Line 1= Truncation Code, Device Information Line 2 = Lot Traceability (Year, Month, Trace Code) **Bottom Mark** No bottom mark		**Top Mark** Line 1= Truncation Code, Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
6	SOT-23		**Top Mark** Line 1= Device Name (shortened) o = Pin 1 indicator **Bottom Mark** Lot Traceability		**Top Mark** Line 1= Device Name (shortened) Lie 2 = Lot Traceability o = Pin 1 indicator **Bottom Mark** No bottom mark
8	VFBGA		**Top Mark** Line 1= Truncation Code, Device Information Line 2 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Truncation Code, Device Information, Year Line 2 = Lot Traceability ● = Pin 1 indicator
49	VFBGA 5X5 MM		**Top Mark** Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Atmel				MICROCHIP	
Lead/Pin/ Bump Count	**Package Description**	**Pre-Change_Marking Diagram (Atmel)**	**Pre-Change_Marking Guidelines (Atmel)**	**Post-Change_Marking Diagram (Microchip)**	**Post-Change_Marking Guidelines (Microchip)**
96	VFBGA 6X6 MM		**Top Mark** Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= LIMES Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability ● = Pin 1 indicator
100	VFBGA 7X7 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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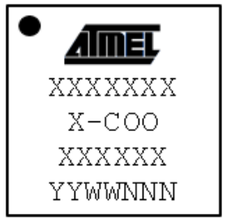
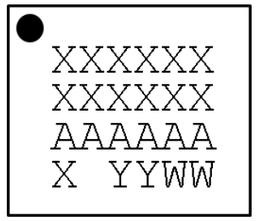
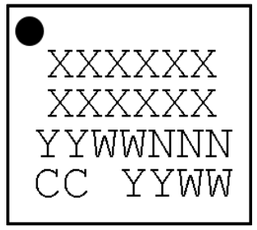
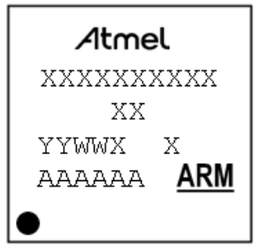
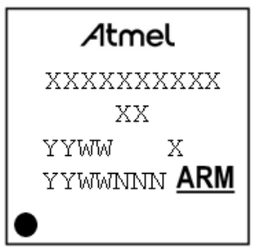
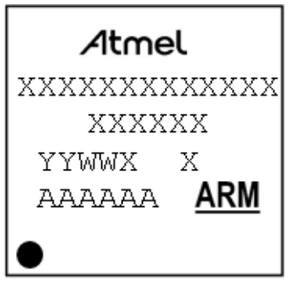
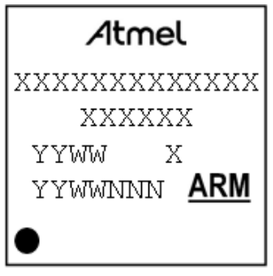
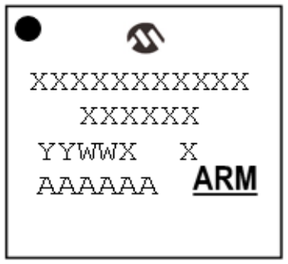
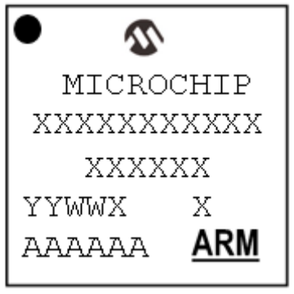
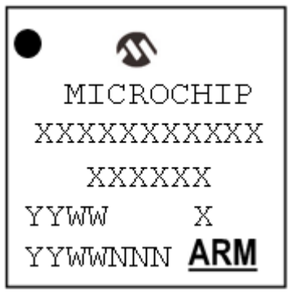
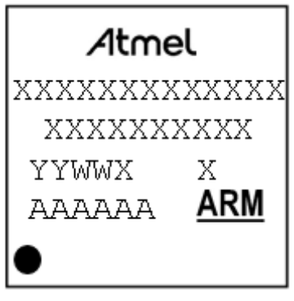
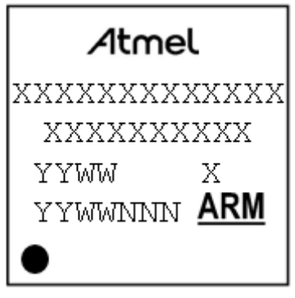
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator
40	TFBGA 4X4 MM		**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Subcon Code, Date Code ● = Pin 1 indicator		**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code ● = Pin 1 indicator
256	TFBGA 8X8 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
100	TFBGA 9X9 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 3 = Country of Assembly Line 4 = Lot Traceability Line 5 = Die ID, Revision ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator
144	TFBGA 10X10 MM		**Top Mark** Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Subcon Code, Design Revision Line 6 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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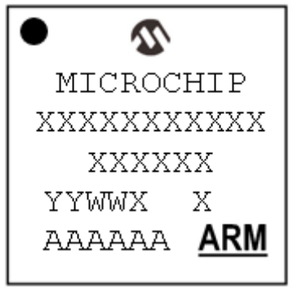
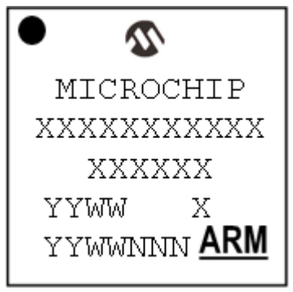
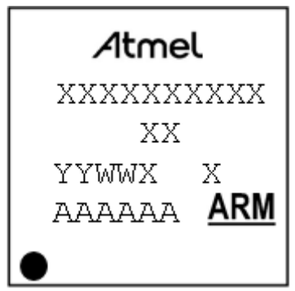
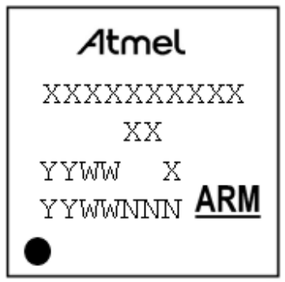
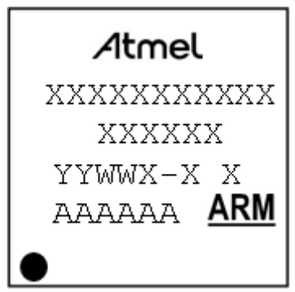
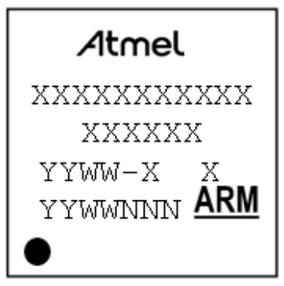
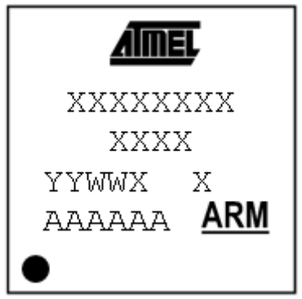
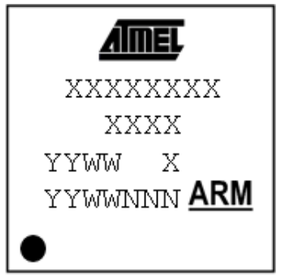
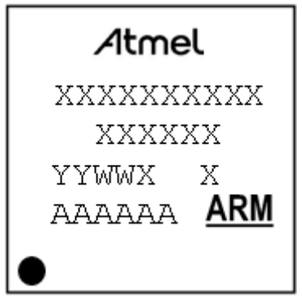
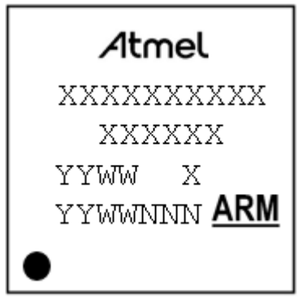
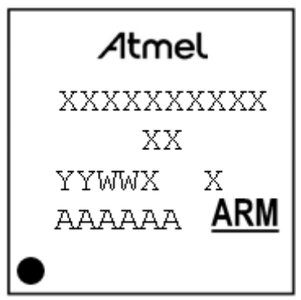
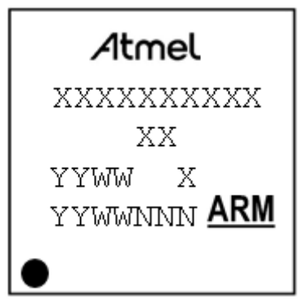
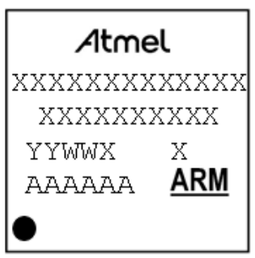
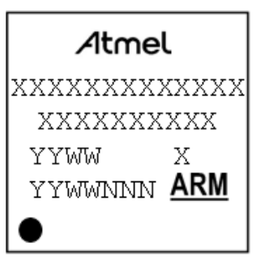
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
176	TFBGA 11X11 MM		**Top Mark** Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Subcon Code, Design Revision Line 6 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Microchip Logo Line 2 = Microchip Line 3 = Device Name Line 4 = Device Information Line 5 = Date Code, Design Revision Line 6 = Lot Traceability, ARM ● = Pin 1 indicator
196	TFBGA 11X11 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

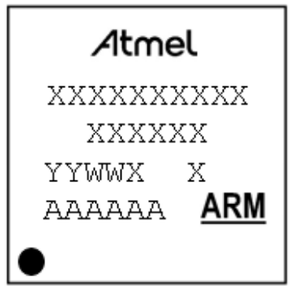
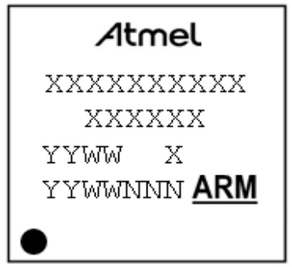
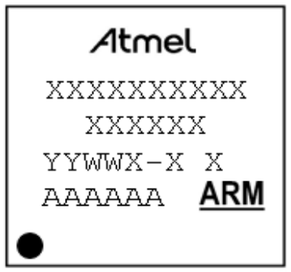
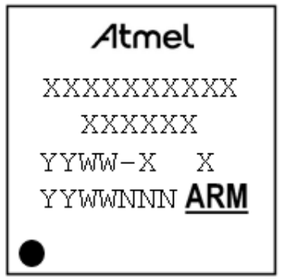
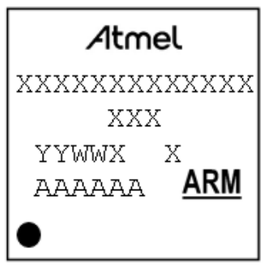
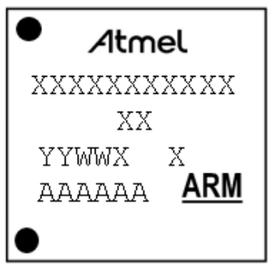
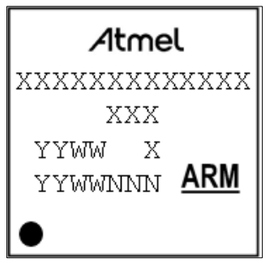
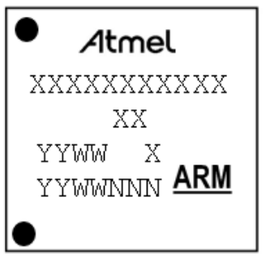
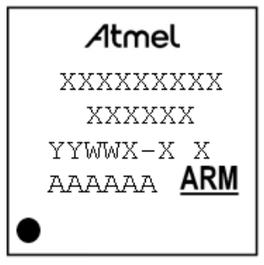
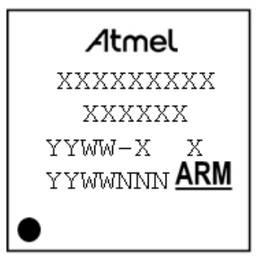
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
144	TFBGA 12X12 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
324	TFBGA 12X12 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
361	TFBGA 16X16 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
144	LFBGA 10X10 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

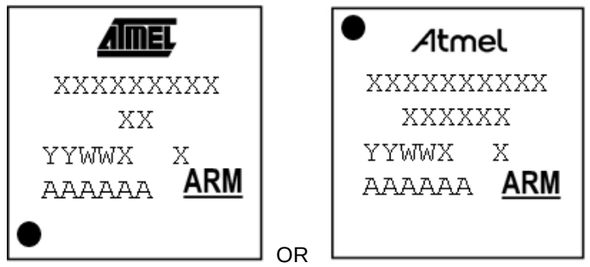
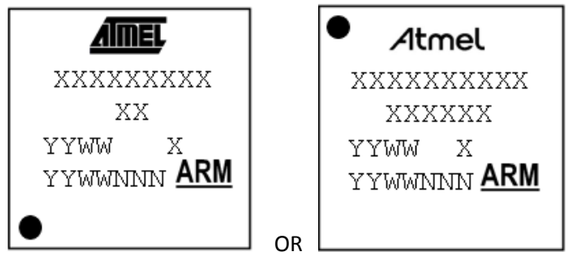
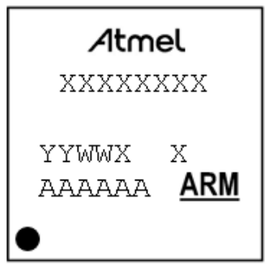
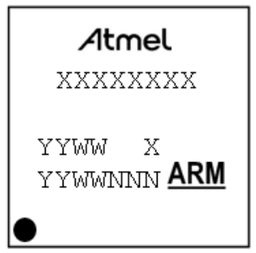
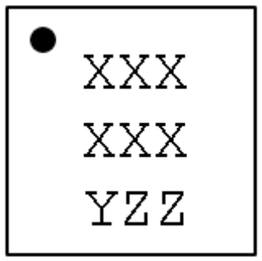
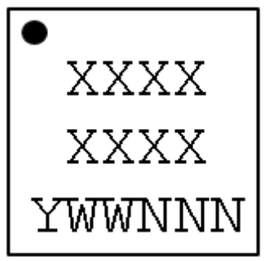
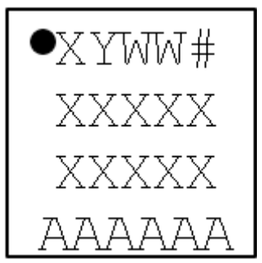
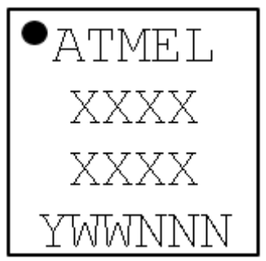
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
289	LFBGA 14X14 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
217	LFBGA 15X15 MM	 OR 	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	 OR 	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
256	LFBGA 15X15 MM	 OR 	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator	 OR 	**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator

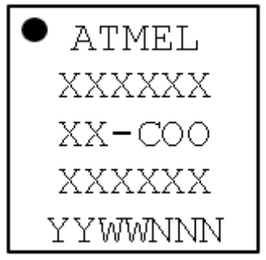
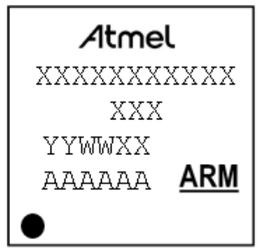
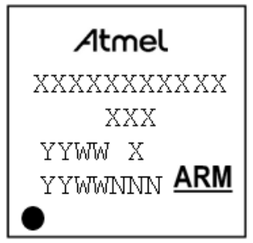
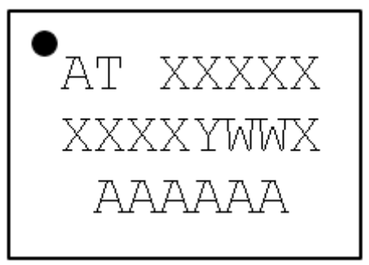
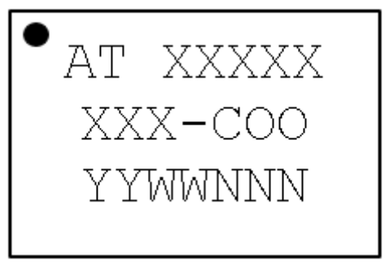
PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Subcon Code, Design Revision Line 4 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Date Code, Design Revision Line 4 = Lot Traceability, ARM ● = Pin 1 indicator
15	UFBGA 3X3 MM		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device Type Code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability ● = Pin 1 indicator
32	UFBGA 4X4 MM		**Top Mark** Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information, Die Revision Line 4 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
49	UFBGA 5X5 MM		**Top Mark** Line 1= AT, Date Code, Die Revision, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Die ID, Revision Line 5 = Lot Traceability ● = Pin 1 indicator
144	UFBGA 6X6 MM		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
			**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Microchip Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
36	WLGA 6.5X3.5 MM		**Top Mark** Line 1= AT, Device Name (shortened) Line 2 = Device Information, Date Code, Die Revision Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= AT, Device Name (shortened) Line 2 = Device Information, Country of Origin Line 3 = Lot Traceability ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

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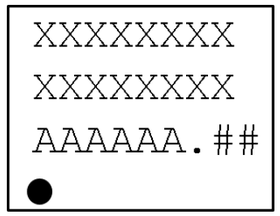
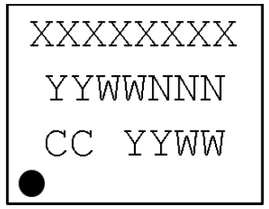
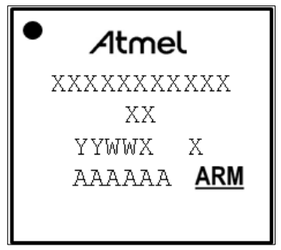
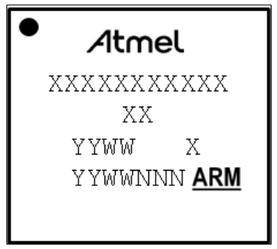
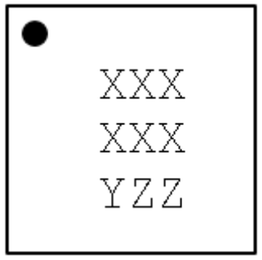
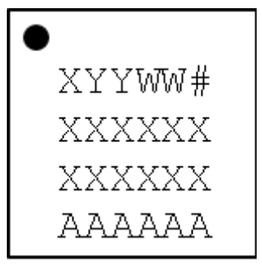
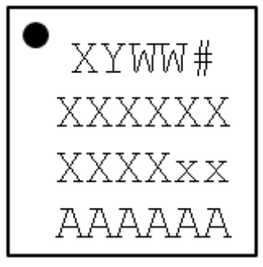
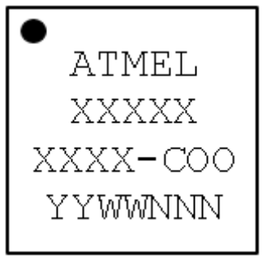
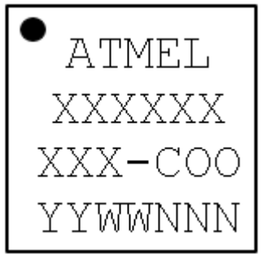
Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
4	WLCSP	● C YTC	**Top Mark** Line 1= Subcon Code Line 2 = Lot Traceability ● = Pin 1 indicator	●WW NNN	**Top Mark** Line 1= Workweek Line 2 = Lot Traceability ● = Pin 1 indicator
8	WLCSP	●CU XXX YTC	**Top Mark** Line 1= Device Information Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator	●XX XXX NNN	**Top Mark** Line 1= Country of Origin Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator
		ATML*YWW XXXXXXXX AAAAAA ●	**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code Line 3 = Lot Traceability ● = Pin 1 indicator	ATML*YWW XXXXXXXX YYWWNNN ●	**Top Mark** Line 1= ATML, Class Code, Date Code Line 2 = Truncation Code, Country of Origin Line 3 = Lot Traceability ● = Pin 1 indicator
31	WLCSP	● XXXXXXXX XXXXXXXX AAAAAA.## X YYWW	**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Date Code ● = Pin 1 indicator	● XXXXXXXX XXXXXXXX YYWWNNN CC YYWW	**Top Mark** Line 1= Device Name Line 2 = Device Information Line 3 = Lot Traceability Line 4 = Country of Origin, Date Code ● = Pin 1 indicator

PART MARKING GUIDELINE (Supplement to PCN# GBNG-15KQFZ896 ADDENDUM)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Lead/Pin/ Bump Count	Package Description	Pre-Change_Marking Diagram (Atmel)	Pre-Change_Marking Guidelines (Atmel)	Post-Change_Marking Diagram (Microchip)	Post-Change_Marking Guidelines (Microchip)
54	WLCSP		**Top Mark** Line 1= Device Name Line 2 = Date Code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Device Name Line 2 = Lot Traceability Line 3 = Country of Origin, Date Code ● = Pin 1 indicator
49 / 64	WLCSP		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Subcon Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator		**Top Mark** Line 1= Atmel Logo Line 2 = Device Name Line 3 = Device Information Line 4 = Date Code, Design Revision Line 5 = Lot Traceability, ARM ● = Pin 1 indicator
20	VQFN 3X3 MM		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code / Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator		**Top Mark** Line 1= Device Name (shortened) Line 2 = Device type code / Class code, Die Revision / Assembly location code Line 3 = Lot Traceability ● = Pin 1 indicator **Bottom Mark** No bottom mark
24 / 28	VQFN 4X4 MM	 OR 	**Top Mark** Line 1= A, Date Code, MRL (if shown in ABI) Line 2 = Device Name Line 3 = Device Information Line 4 = Lot Traceability ● = Pin 1 indicator	 OR 	**Top Mark** Line 1= ATMEL Line 2 = Device Name Line 3 = Device Information, Country of Origin Line 4 = Lot Traceability ● = Pin 1 indicator